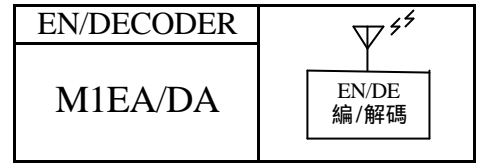




SAME Rosc in EN/DE  
S.O.DIP

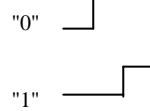
使用同一電阻



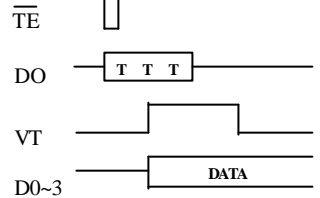
**FEATURES 功能敘述**

- Momentary DATA suffix-M.
- S.O.Package 18P suffix-S.
- Direct Data Transmit suffix-H : switch to VDD.

**BIT FORMAT**



**PROTOCOL**



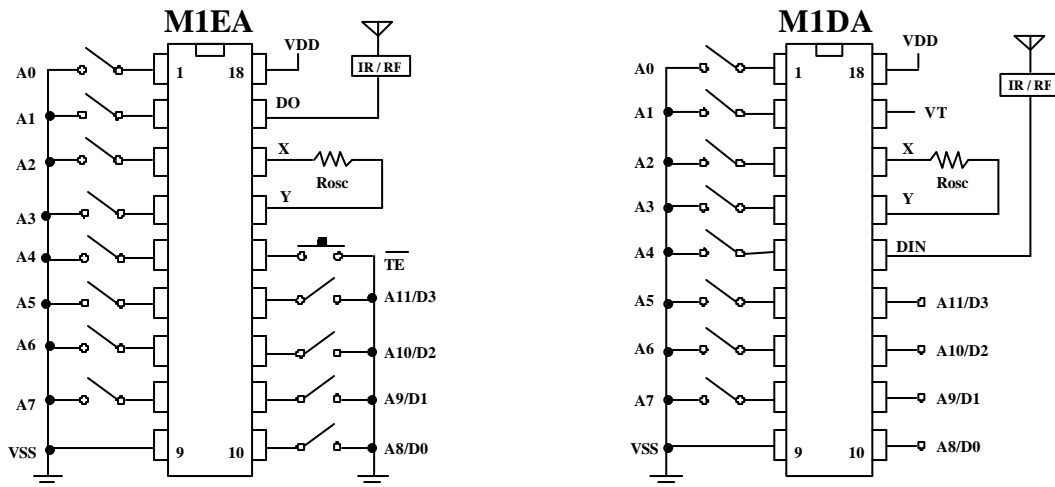
**APPLICATION 產品應用**

Security alarm, Remote control. 防盜系統, 任何遙控裝置.

**ELECTRICAL CHARACTERISTICS 電氣規格**

Characteristics	Sym.	Min.	Typ.	Max.	Unit	REMARKS
工作電壓 Operating Voltage	V <sub>DD</sub>	2.4		13	V	
工作電流 Operating Current	I <sub>OP</sub>		0.1	1	mA	No load
靜態電流 Quiescent Current	I <sub>SB</sub>		1	10	uA	
推動電流 Driving Current	I <sub>OL</sub>		2		mA	@ V <sub>DS</sub> =1.2V
振盪頻率 Oscillator Frequency	F <sub>OSC</sub>		76		KHz	External ±30%
工作溫度 Operating Temperature	Temp.	-20	25	60		

**APPLICATION DIAGRAM 參考電路圖**




\* Rosc~M1EA : 270 K , M1DA : 270 K

\* All specs and applications shown above subject to change without prior notice.  
( 以上電路及規格僅供參考,本公司得逕行修正 )



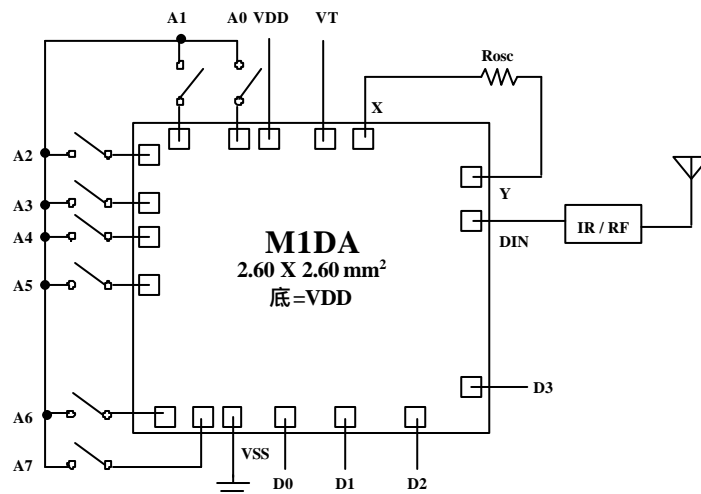
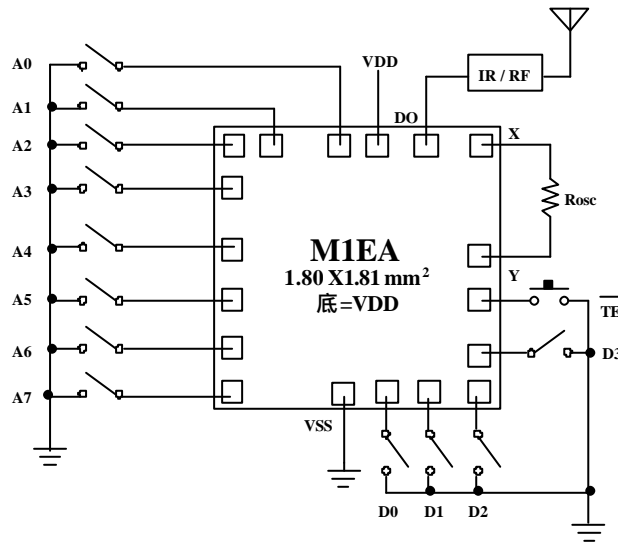
SAME Rosc in EN/DE  
S.O.DIP

使用同一電阻

EN/DECODER	
M1EA/DA	

APPLICATION DIAGRAM 參考電路圖

CHIP FORM



\* Rosc~M1EA : 270 K , M1DA : 270 K

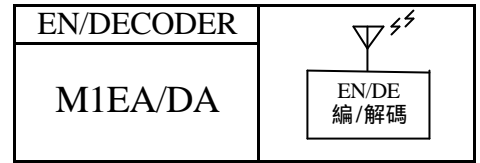
\* All specs and applications shown above subject to change without prior notice.

( 以上電路及規格僅供參考,本公司得逕行修正 )



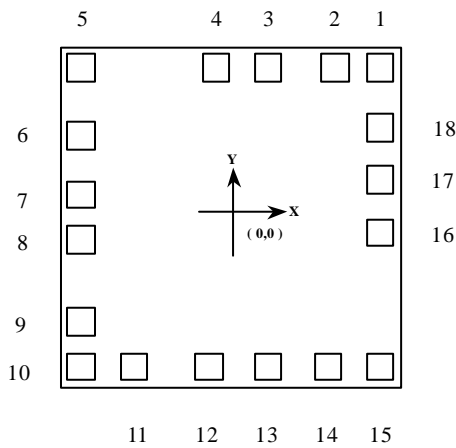
SAME R<sub>osc</sub> in EN/DE  
S.O.DIP

使用同一電阻



**PAD ASSIGNMENT & POSITION**

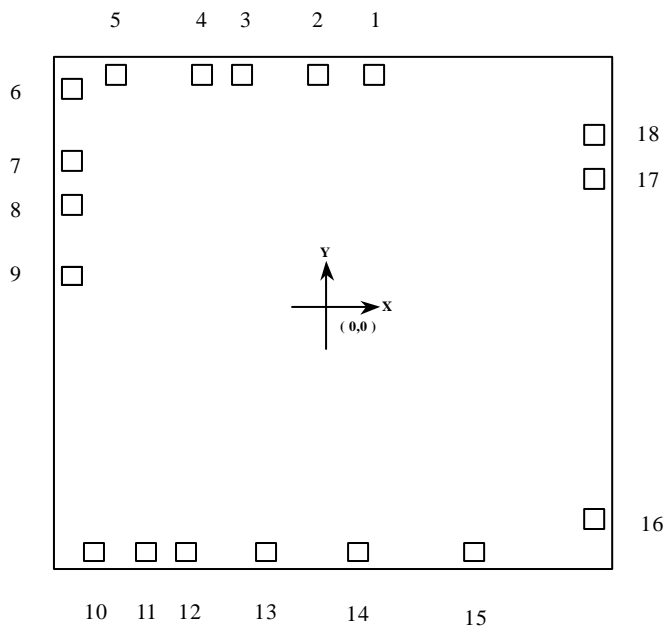
**M1EA :**



UNIT :  $\mu\text{m}$

No.	NAME	X	Y
1	A10 / D2	728	732.5
2	A11 / D3	528	732.5
3	TEB	211	732.5
4	Y	-31.5	732.5
5	X	-728.5	732.5
6	DOUT	-728.5	376.5
7	VDD	-728.5	36
8	A0	-728.5	-164
9	A1	-728.5	-533
10	A2	-728.5	-733
11	A3	-480.5	-733
12	A4	-101	-733
13	A5	184	-733
14	A6	480	-733
15	A7	728	-733
16	VSS	728	-66
17	A8 / D0	728	183
18	A9 / D1	728	431.5

**M1DA :**



UNIT :  $\mu\text{m}$

No.	NAME	X	Y
1	X	259.5	1096.5
2	VT	-9.5	1096.5
3	VDD	-347	1096.5
4	A0	-547	1096.5
5	A1	-950	1096.5
6	A2	-1150	1025
7	A3	-1150	702
8	A4	-1150	502
9	A5	-1150	179
10	A6	-1043	-1100
11	A7	-799.5	-1100
12	VSS	-599.5	-1100
13	A8 / D0	-251	-1100
14	A9 / D1	169	-1100
15	A10 / D2	696	-1100
16	A11 / D3	1145.5	-946
17	DIN	1086	590
18	Y	1086	790

\* M1EA CHIP SIZE ~ 1.80 X 1.81 mm<sup>2</sup>

\* M1DA CHIP SIZE ~ 2.60 X 2.60 mm<sup>2</sup>

\* IC substrate should be connected to VDD in PCB (PCB 上 IC 必須接 VDD)